SMD Power Choke Coil

TMPC1004H-Series(G)-D

	ECN HISTORY LIST								
REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN				
1.0	13/03/25	新 發 行	楊祥忠	羅培君	徐允珮				
備									
HΗ									
註									

SMD Power Choke Coil

TMPC1004H-Series(G)-D

1. Features

- 1. Carbonyl powder inductor.
- 2. Compact design.
- 3. High current , low DCR , high efficiency.
- 4. Very low acoustic noise and very low leakage flux noise.
- 5. High reliability.
- 6. 100% Lead(Pb) & Halogen-Free and RoHS compliant.

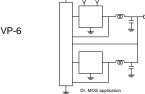




2. Applications

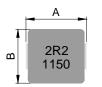
3. Dimensions

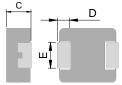
Note PC power system , incl. IMVP-6 DC/DC converter.



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Recommend PC Board Pattern







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Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
TMPC1004H	11.0±0.5	10.0±0.3	3.8±0.2	2.3±0.3	3.0±0.3

4. Part Numbering



A: Series

B: Dimension BxC

C: Type Carbonyl powder
D: Inductance 2R2=2.20uH
E: Inductance Tolerance M=±20%

F: D/C 印字:黑色; 2R2 及 D/C 1150 (D/C 前二碼是年份,後二碼是週期,依實際生產週期而定)

5. Specification

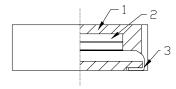
Part Number	Inductance L0 (uH) @ 0 A	I rms (A) typ.	I sat (A) typ.	DCR (mΩ) typ. @25℃	DCR (mΩ) max. @25℃
TMPC1004H-R22MG-D	0.22	35	60	0.8	1.0
TMPC1004H-R27MG-D	0.27	33	60	0.82	1.0
TMPC1004H-R36MG-D	0.36	31	60	1.05	1.2
TMPC1004H-R39MG-D	0.39	30	60	1.1	1.3
TMPC1004H-R45MG-D	0.45	29	45	1.3	1.5
TMPC1004H-R56MG-D	0.56	25	40	1.6	1.8
TMPC1004H-1R0MG-D	1.00	18	36	3.0	3.3
TMPC1004H-1R5MG-D	1.50	16	33	4.0	4.6
TMPC1004H-2R2MG-D	2.20	12	27	6.5	7.0
TMPC1004H-3R3MG-D	3.30	11	20	10.8	11.8
TMPC1004H-4R7MG-D	4.70	10	17	15.0	15.5
TMPC1004H-6R8MG-D	6.80	8.5	13.5	17.5	23.3
TMPC1004H-8R2MG-D	8.20	8.0	12.5	20	22.5
TMPC1004H-100MG-D	10.0	7.5	12.0	27.0	30
TMPC1004H-150MG-D	15.0	6.25	10	40	45

Part Number	Inductance L0 (uH) @ 0 A	l rms (A) typ.	I sat (A) typ.	DCR (mΩ) typ. @25℃	DCR (mΩ) max. @25℃
TMPC1004H-220MG-D	22.0	5.0	7.0	64	74
TMPC1004H-330MG-D	33.0	3.5	5.0	92	112

Note:

- 1. Test frequency : L : 100KHz /1.0V
- 3. Testing Instrument: L/Q: HP4284A,CH11025,CH3302,CH1320 ,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
- 4. Heat Rated Current (Irms) will cause the coil temperature rise approximately $\Delta t \le 40^{\circ}$ C (keep 1min.).
- 5. Saturation Current (Isat) will cause L0 $\,$ to drop $\,\leq\,$ 20% typical. (keep quickly).
- 6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

6. Material List



NO	Items	Materials	
1	Core	Carbonyl powder or equ.	
2	Wire	Polyester Wire or equivalent.	
3	Solder Plating	100% Pb free solder	

7. Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125℃	
Storage temperature and Humidity range	-40~+125℃ (For products in unopened tape package, less than 40℃) 50~60%RH (Product without taping)	
Electrical Performance Te	st	
Inductance	Refer to standard electrical characteristics list.	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.
DCR	Note to standard electrical characteristics list.	CH16502,Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	△L≦20% typical.	Saturation DC Current (Isat) will cause L0 to drop △L(%)(keep quickly).
Heat Rated Current (Irms)	Approximately △T ≤40°C	Heat Rated Current (Irms) will cause the coil temperature rise △T(C) without core loss. 1.Applied the allowed DC current(keep 1 min.). 2.Temperature measured by digital surface thermometer
Reliability Test		
High Temperature Exposure Tes	t	Temperature:125±2°C. Duration:500±8hrs. Measured at room temperature after placing for 2 to 3hrs. (MIL-STD-202 Method 108)
Low Temperature Life Test		Temperature:-40±2°C. Duration:500±8hrs. Measured at room temperature after placing for 2 to 3hrs. (UESD22-A119)
Biased Humidity Test		Humidity:90–95%. Temperature:40±2°C. Duration:500±8hrs. Measured at room temperature after placing for 2 to 3hrs (AEC-Q200-REV C)
Thermal shock test	Electric specifications should be satisfied	Condition for 1 cycle $ \begin{array}{ll} \text{Step1:-40+0} \ / \ -2^{\circ}\mathbb{C} & 15\pm 1 \text{ min.} \\ \text{Step2:Room temperature within } \leq 0.2 \text{ min.} \\ \text{Step3:+125+2} \ / \ -0^{\circ}\mathbb{C} & 15\pm 1 \text{min.} \\ \text{Number of cycles:300} \\ \text{Measured at room temperature after placing for 2 to 3 hrs.} \\ \text{(AEC-Q200)} \\ \end{array} $
Vibration test		Frequency: 10-2000-10Hz for 20 min. Amplitude: Parts mounted within 2" from any secure point. Directions and times: X, Y, Z directions for 20 min. This cycle shall be performed 12 times in each of three mutually perpendicular directions (Total 12hours). (MIL-STD-202 Method 204 D Test condition B)
Reflow test		Pre-heat : 150±5°C Duration : 5 minutes Temperature : 260±5°C · 20~40 seconds (IPC/JEDEC J-STD-020C)
Solder test	Terminals should be covered by over 95% solder on visual inspection	After dip into flux ⋅ dip into solder 235±5℃ ⋅ 4±1seconds Flux ⋅ solder for lead free (ANSI /J-STD-002C Method B)

8. Soldering and Mounting

(1) Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

Note

If Use Wave soldering is there will be some risk. Re-flow soldering temperatures below 240 degrees, there will be unwitting risk

(2) Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

(3) Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- Preheat circuit and products to 150℃
- · Never contact the ceramic with the iron tip
- · Use a 20 watt soldering iron with tip diameter of 1.0mm
- 355 $^{\circ}$ C tip temperature (max) 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.

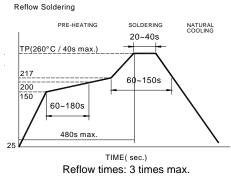
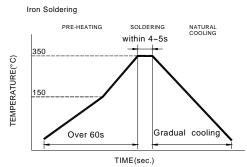


Fig.1

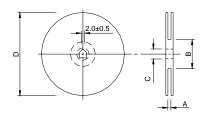


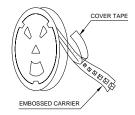
Iron Soldering times: 1 times max.

Fig.2

9. Packaging Information

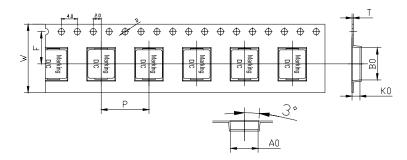
(1) Reel Dimension





Туре	A(mm)	B(mm)	C(mm)	D(mm)
13"x24mm	24.0±0.5	100±2	13.5±0.5	330

(2) Tape Dimension

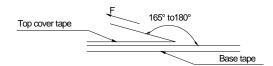


Series	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	t(mm)	D(mm)
TMPC	1004	11.7±0.1	10.5±0.1	4.5±0.1	16.0±0.1	24±0.3	11.5±0.1	0.35±0.05	1.5±0.1

(3) Packaging Quantity

ТМРС	1004
Chip / Reel	500
Inner box	1000
Carton	4000

(4) Tearing Off Force



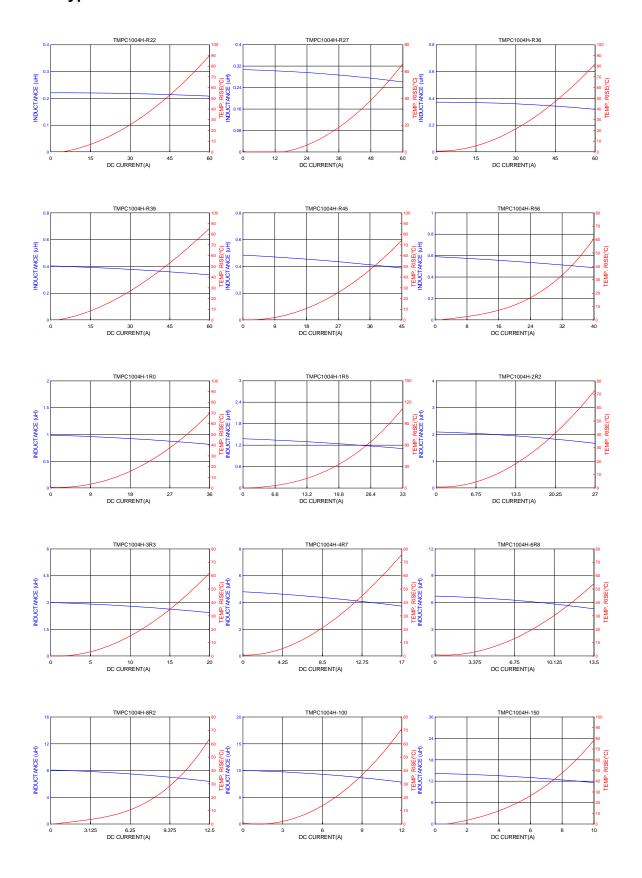
The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-C-2003 of 4.11 stadnard).

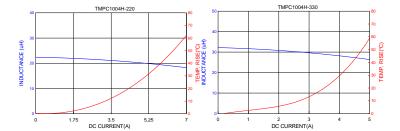
Room Temp. Room Humidity		Room atm	Tearing Speed
(℃)	(%)	(hPa)	mm/min
5~35	45~85	860~1060	300

Application Notice

- Storage Conditions
- To maintain the solderability of terminal electrodes:
- 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 3. Recommended products should be used within 12 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
- 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

10. Typical Performance Curves







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西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

1000

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(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

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(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

以下測試樣品係由客户送樣,且由客户聲稱並經客户確認如下 (The following samples was/were submitted and identified by/on behalf of the client as):

樣品名稱(Sample Description)

: SMD POWER INDUCTOR

樣品型號(Style/Item No.)

: TMPB, TMPC, SLPI, SMPI, SMPI-P3, EPI(ePI), VMPI, MLPI, SEPI, HCM SERIES

收件日期(Sample Receiving Date)

: 2013/01/25

測試期間(Testing Period)

: 2013/01/25 TO 2013/02/01

測試結果(Test Results) : 請見下一頁 (Please refer to next pages).



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Test Report

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(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

測試結果(Test Results)

測試部位(PART NAME)No.1 : 整體混測 (MIXED ALL PARTS)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鐍 / Cadmium (Cd)	mg/kg	参考IEC 62321: 2008方法,以感應耦合電 漿原子發射光譜儀檢測. / With reference to IEC 62321: 2008 and performed by ICP-AES.	2	n.d.
鋁 / Lead (Pb)	mg/kg	参考IEC 62321: 2008方法,以感應耦合電 漿原子發射光譜儀檢測. / With reference to IEC 62321: 2008 and performed by ICP-AES.	2	n.d.
汞 / Mercury (Hg)	mg/kg	参考IEC 62321: 2008方法,以感應耦合電 漿原子發射光譜儀檢測./ With reference to IEC 62321: 2008 and performed by ICP-AES.	2	n.d.
六價鉻 / Hexavalent Chromium Cr(VI)	mg/kg	多考IEC 62321: 2008方法,以UV-VIS檢測. / With reference to IEC 62321: 2008 and performed by UV-VIS.	2	n.d.
绨 / Antimony (Sb)	mg/kg	參考US EPA 3050B方法,以感應耦合電漿原 子發射光譜儀檢測. / With reference to US EPA 3050B. Analysis was performed by ICP-AES.	2	n.d.

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Test Report

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
多溴聯苯蟌和 / Sum of PBBs	mg/kg		_	n.d.
一溴聯苯 / Monobromobiphenyl	mg/kg		5	n.d.
二溴聯苯 / Dibromobiphenyl	mg/kg		5	n.d.
三溴聯苯 / Tribromobiphenyl	mg/kg		5	n.d.
四溴聯苯 / Tetrabromobiphenyl	mg/kg		5	n.d.
五溴聯苯 / Pentabromobiphenyl	mg/kg		5	n.d.
六溴聯苯 / Hexabromobiphenyl	mg/kg		5	n.d.
七溴聯苯 / Heptabromobiphenyl	mg/kg		5	n.d.
へ溴聯苯 / Octabromobiphenyl	mg/kg		5	n.d.
九溴聯苯 / Nonabromobiphenyl	mg/kg		5	n.d.
十溴聯苯 / Decabromobiphenyl	mg/kg	参考IEC 62321: 2008方法,以氣相層析/質 譜儀檢測. / With reference to IEC 62321: 2008 and performed by GC/MS.	5	n.d.
多溴聯苯醚總和 / Sum of PBDEs	mg/kg		-	n.d.
- 澳聯苯醚 / Monobromodiphenyl ether	mg/kg		5	n.d.
二溴聯苯醚 / Dibromodiphenyl ether	mg/kg		5	n.d.
三溴聯苯醚 / Tribromodiphenyl ether	mg/kg		5	n.d.
四溴聯苯醚 / Tetrabromodiphenyl ether	mg/kg		5	n.d.
五溴聯苯醚 / Pentabromodiphenyl ether	mg/kg		5	n.d.
六溴聯苯醚 / Hexabromodiphenyl ether	mg/kg		5	n.d.
ヒ溴聯苯醚 / Heptabromodiphenyl ether	mg/kg		5	n.d.
∖溴聯苯醚 / Octabromodiphenyl ether	mg/kg		5	n.d.
C溴聯苯醚 / Nonabromodiphenyl ether	mg/kg		5	n.d.
├溴聯苯醚 / Decabromodiphenyl ether	mg/kg		5	n.d.

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値	結果 (Result)
鹵素 / Halogen			(MDL)	No.1
鹵素(氟)/ Halogen-Fluorine (F) (CAS No.: 14762-94-8)	mg/kg		50	n.d.
鹵素(氣)/ Halogen-Chlorine (CI) (CAS No.: 22537-15-1)		参考BS EN 14582:2007, 以離子層析儀分析, / With reference to BS EN 14582:2007, Analysis was performed by IC.	50	n.d.
鹵素(溴)/ Halogen-Bromine (Br) (CAS No.: 10097-32-2)			50	n.d.
鹵素(碘)/ Halogen-Iodine (I) (CAS No.: 14362-44-8)	mg/kg		50	n.d.

備註(Note):

- 1. mg/kg = ppm; 0.1wt% = 1000ppm
- 2. n.d. = Not Detected (未检出)
- 3. MDL = Method Detection Limit (方法偵測極限値)
- 4. "-" = Not Regulated (無規格値)
- 5. 樣品的測試是基於申請人要求混合測試,報告中的混合測試結果不代表其中個别單一材質的含量. (The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)
- 6. 此份報告取代簽署人為Chenyu Kung之CE/2013/15715報告. (This report supersedes the previous document bearing the test report number CE/2013/15715 which signed by Chenyu Kung.)

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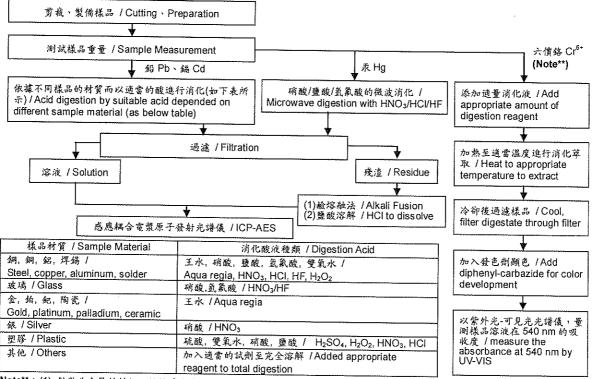
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(廣東省東莞市黄江鎮黄牛埔福祥街2號 / NO. 2, FUXIANG STREET, HUANGNIUPU, HUANGJIANG TOWN, DONGGUAN,

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, IANG-SU, CHINA)

- 1) 根據以下的流程圖之條件,樣品已完全溶解。(六價格測試方法除外) / These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr⁶⁺ test method excluded)
- 測試人員:楊登律 / Name of the person who made measurement: Climbgreat Yang
- 測試負責人: 張啓興 / Name of the person in charge of measurement: Troy Chang



Note**: (1) 針對非金屬材料加入鹼性消化液,加熱至 90~95℃萃取. / For non-metallic material, add alkaline digestion reagent and heat to 90~95℃.

(2) 針對金屬材料加入純水,加熱至沸騰萃取 / For metallic material, add pure water and heat to boiling.

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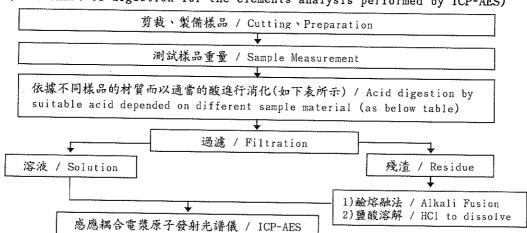
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- 1) 根據以下的流程圖之條件,樣品已完全溶解。 / These samples were dissolved totally by pre-conditioning method according to below flow chart.
- 2) 測試人員:楊登律 / Name of the person who made measurement: Climbgreat Yang
- 3) 測試負責人:張啓興 / Name of the person in charge of measurement: Troy Chang

元素以 ICP-AES 分析的消化流程圖

(Flow Chart of digestion for the elements analysis performed by ICP-AES)



鋼,銅,鋁,焊錫 / Steel, copper, aluminum, solder	王水,硝酸,鹽酸,氫氟酸,雙氧水 /
	Aqua regia, HNO3, HC1, HF, H2O2
玻璃 / Glass	硝酸,氫氟酸 / HNO ₃ /HF
金,鉑,鈀,陶瓷 / Gold, platinum, palladium, ceramic	王水 / Aqua regia
銀 / Silver	硝酸 / HNOa
塑膠 / Plastic	硫酸, 雙氧水, 硝酸, 鹽酸 / HzSO4, HzO2, HNO3, HC1
其他 / Others	加入適當的試劑至完全溶解 / Added appropriate
	reagent to total digestion

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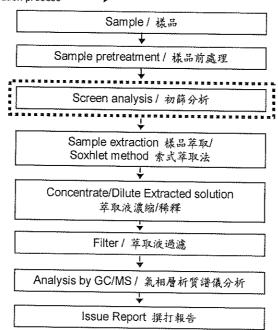
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多溴聯苯/多溴聯苯醚分析流程圖 / PBB/PBDE analytical FLOW CHART

- 測試人員: 翁賜彬 / Name of the person who made measurement: Roman Wong
- 測試負責人:張啓興 / Name of the person in charge of measurement: Troy Chang 初次测试程序 / First testing process -選擇性篩檢程序 / Optional screen process ■■■■

確認程序 / Confirmation process - . - . -



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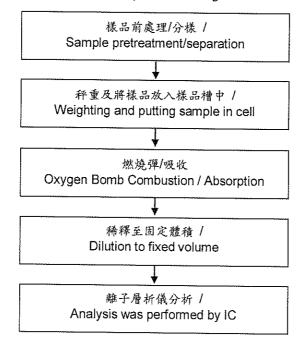
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鹵素分析流程圖 / Analytical flow chart of halogen content

- 1) 測試人員: 陳恩臻 / Name of the person who made measurement: Rita Chen
- 2) 測試負責人:張啓興 / Name of the person in charge of measurement: Troy Chang



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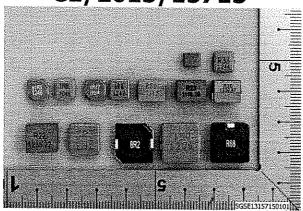
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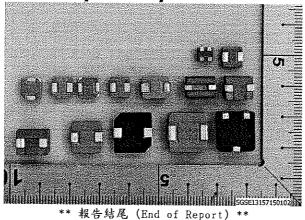
* 照片中如有箭頭標示,則表示為實際檢測之樣品/部位. *

(The tested sample / part is marked by an arrow if it's shown on the photo.)

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